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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hideyuki TANIMOTO	11/05/2010
Takuya KONNAI	11/01/2010
Kouji SAGAWA	11/05/2010

RECEIVING PARTY DATA

Name:	HITACHI KOKI CO., LTD.	
Street Address:	15-1, Kounan 2-chome, Minato-ku,	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	108-6020	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12974523

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Brian K. Seidleck	

Total Attachments: 3

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PATENT REEL: 025539 FRAME: 0438 source=085820-0026_asgn#page3.tif

PATENT REEL: 025539 FRAME: 0439 Docket No.:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,				
(1) Hidevuki TANIMOTO (4)				
(1) Hideyuki TANIMOTO (4) (2) Takuya KONNAI (5) (3) Kouji SAGAWA (6)				
(3) Kouji SAGAWA (6)				
who have made a certain new and useful invention, hereby sell, assign and transfer unto				
HITACHI KOKI CO., LTD.				
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled				
DUST COLLECTOR				
(a) for which an application for United States Letters Patent was filed on, and identified by United States Serial No; or				
(b) for which an application for United States Letters Patent was executed on,				
and the undersigned hereby authorize and request the United States Commissioner for Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;				
AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued				

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

PATENT REEL: 025539 FRAME: 0440 SIGNED on the dates indicated aside our signatures:

	INVENTORS	DATE SIGNED
1)	Name: Hideyuki TANIMOTO	11/5/20/0
	Name: Hideyuki TANIMOTO	
2)	Name: Takuya KONNAI	11/1/2010
	Name: Takuya KONNAI	
3)	Kouji Sagawa Name: Kouji SAGAWA	11/5/2010
	Name: Kouii SAGAWA	

PATENT REEL: 025539 FRAME: 0441

RECORDED: 12/21/2010